Guidelines for Article Contributors
2009-2010

Original, well-written technical articles are essential for ***Wafer & Device Packaging and Interconnect*** magazine. We welcome your contributions!

We understand that it requires a significant amount of work to prepare an article for our well-educated, highly literate readership and we want to help you as much as possible. Ultimately, the publication of contributed articles represents a team effort by our contributors, and the editors and production staff of ***Wafer & Device Packaging and Interconnect***.

By following the guidelines below, you will expedite the processing of your article through acceptance, editing, production and publication. While you may submit a completed article, we suggest submitting an abstract of 200-300 words before beginning.

Requirement and Suggestions:

- Be original to ***Wafer & Device Packaging and Interconnect***. We do not accept articles that have been printed in another publication. Papers that have been presented at conferences and published in proceedings are welcome but should be rewritten in Wafer & Device Packaging and Interconnect's magazine style. A reference must be provided as to where and when the paper was presented. Please contact the organization involved to see if they have any required credit line that must be used. Usually, there is a standard credit line that they will want to use. It is the author's responsibility to obtain the necessary authorization to use the paper as an article.
- Advance the state of knowledge of wafer-level packaging (WLP) and devices (ICs and MEMS, either single or 3D and 2D multichip packages). This includes WLP wafer-fab packaging specific processes and back-end process steps such as via first, CMP thinning/polishing, underbump redistribution layers (UBM RDL), wafer plating and bumping, and wafer and die stacking/bonding. Many processes now use through silicon via interconnects (TSVs) for advanced IC/MEMS assembly/packaging. This includes the many System-in-Package (SiP), System-on-Package (SoP), Package-on- Package (PoP), Chip-on-Wafer (CoW) or other multichip 2D/3D package variants – each with some pragmatic size, manufacturing and cost advantages. Via first, via middle and via last are all viable options. Lower cost TSVs with requisite performance will win out.

WDPI is always interested in significant mainstream test, assembly and packaging advances since they are the backbone of the industry. Processes and technologies evolve and prove to be useful over the decades. Although "new" is always intriguing, most real-world assembly and packaging is a mix of well-established and new processes. Wire bonding is still widely used and there is always some new bumping process to consider. Somewhere, in a lab, a "next generation" process is being evaluated.

Wafer & Device Packaging and Interconnect also covers the high-density interconnect (HDI) organic and inorganic substrates and interposers that are essential for multichip package implementations and embedding active and passive components in substrates. We are also interested in articles that address integrating ICs with other nanotechnology, MOEMS, RF/wireless and optoelectronic/photonic devices.

- Be free of commercialism.
- Be well written with solid technical content that will be understandable by the majority of our readers.
- Never submit the same article to more than one publication at the same time!

Review

To ensure the highest quality in our publication, most contributed articles are reviewed by the staff editors and outside experts. Some articles are returned to the author for revisions. Keep in mind that we work in advance of the publication date. For example, an article submitted in early January is unlikely to be published prior to the March or April. After your article has been typeset, you will receive a review copy in the form of a PDF file.

Important: While we will endeavor to publish your article in the scheduled issue when it is received by our stated deadline, production considerations or an insufficient amount of available editorial space – or both – may require that we delay publication until a future issue as is the case with most magazines.

In addition to the article, you must include a brief bio of each author (75-100) words. This bio should indicate current job title, former job title and industry experience, educational background and an e-mail address for readers to contact the author(s). A copyright transfer form must also be submitted.

Mechanical Requirements

- Submit your article as a Word file (either Windows or Macintosh version with .doc file extension – not .docx or .pdf files). This file should be in one column. Most authors now submit the article and illustrations via e-mail using zip compression for all files them before sending them.
- Do not include the graphics embedded in your Word file. These should be in separate image files with the file identification stated above figure captions.
- Graphics generated in Adobe Illustrator and Adobe Photoshop/Photoshop Elements are preferred. The files should be submitted as .eps, .jpg, .psd or .tif.
- Unless otherwise requested, your article should be between 1500-2500 words in length with 5 or 6 illustrations. If your article covers a process that may be unfamiliar to many of our readers, it will be helpful to include a glossary that would shown be in a sidebar.
- We suggest that you show your article to colleagues within or outside your company before submitting it to us. Their comments will help ensure that your writing is understandable and useful to the intended audience.
- We will edit, but will not rewrite your article for style, syntax, spelling and grammar, but your article must be cohesive when you submit it.

Illustrations

- Photos must be minimum of 300 dpi or larger at 4 x 5 inches. Do not submit 72 dpi images; these are suitable for web use only.
- Except where the intent is clear that photos from a website may be used for editorial purposes, you must not download photos from websites to include in your article without the website owner's permission. It is not sufficient to give credit to a "borrowed" illustration. Except where permission is given at the website, you must obtain permission of the original copyright owner.
- You are strongly urged to include individual, professional, high resolution color photo(s) of the author(s) with the article. Additionally, we normally do not use black and white photos in ***Wafer & Device Packaging and Interconnect*** except where the original is b/w, such as an SEM photo.

Suggestions

- Outline: Composing a brief outline before writing the article will help you organize your thoughts. It will also help keep the flow of information smooth and organized.
- Use Short Sentences: Cramming too much information into one sentence is a common mistake. Use two or more sentences, if needed, for clarity.
- Sidebar: Background information needed to fully explain your article may take the form of a sidebar. This is a supplement to your article and might contain definitions, addresses or a lengthy explanation.
- Introduction: Beginning your article with a short abstract is helpful. This should be as interesting as possible because the reader may decide to continue reading (or not) at this point.
- Avoid Clichés: Nothing can dampen reader interest faster than overworked phrases and buzzwords.
- Keep It Simple: A technical article should not be used as a showcase for an extensive vocabulary. Don't use four or five words when you can use one.
- For other suggestions concerning grammar, spelling and structure, one of our favorite reference studies is The Elements of Style by Strunk and White. It is informative, funny, inexpensive, and it will help you write a better article.

Please contact the Executive Editor, Terry Thompson,
[TerrenceThompson@att.net], with any questions.